

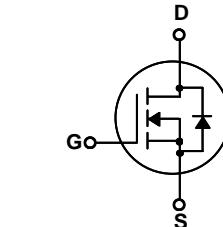
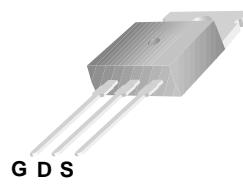


WFP8N60

600V N-Channel MOSFET

Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge : $Q_g = 40\text{nC}$ (Typ.)
- $\text{BV}_{DSS} = 600\text{V}, \text{ID} = 7.5\text{A}$
- $R_{DS(on)} : 1.32 \Omega$ (Max) @ $\text{VG} = 10\text{V}$
- 100% Avalanche Tested



TO-220

G-Gate,D-Drain,S-Source

Absolute Maximum Ratings $T_c = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	WFP8N60	Units
V_{DSS}	Drain-Source Voltage	600	V
I_D	Drain Current -continuous ($T_c = 25^\circ\text{C}$)	7.5	A
	-continuous ($T_c = 100^\circ\text{C}$)	4.7	A
V_{GS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Plused Avalanche Energy (Note1)	420	mJ
I_{AR}	Avalanche Current (Note2)	7	A
P_D	Power Dissipation ($T_c = 25^\circ\text{C}$)	147	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 ~ +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	--	0.88	$^\circ\text{C/W}$
$R_{\theta CS}$	Thermal Resistance,Case to Sink	0.5	--	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	--	62.5	$^\circ\text{C/W}$

Electrical Characteristics T_c=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	ID=250 μA, VGS=0	600	--	--	V
△BV _{DSS} / △T _J	Breakdown Voltage Temperature Coefficient	I _D =250 μA, Reference to 25°C	--	0.67	--	V/°C
IDSS	Zero Gate Voltage Drain Current	V _{DS} =600V, V _{Gs} =0V	--	--	10	μA
		V _{DS} =480V, T _c =125°C			100	μA
IGSSF	Gate-body leakage Current, Forward	V _{Gs} =+30V, V _{DS} =0V	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	V _{Gs} =-30V, V _{DS} =0V	--	--	-100	nA

On Characteristics

V _{GS(th)}	Date Threshold Voltage	I _d =250uA, V _{DS} =V _{Gs}	2	--	4	V
R _{DS(on)}	Static Drain-Source On-Resistance	I _d =3.7A, V _{Gs} =10V	--	--	1.32	Ω

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} =25V, V _{Gs} =0, f=1.0MHz	--	1100	1430	pF
C _{oss}	Output Capacitance		--	135	175	pF
C _{rss}	Reverse Transfer Capacitance		--	16	21	pF

Switching Characteristics

T _{d(on)}	Turn-On Delay Time	VDD=300V, ID=7A RG=25Ω (Note 3,4)	--	30	70	nS
T _r	Turn-On Rise Time		--	80	170	nS
T _{d(off)}	Turn-Off Delay Time		--	65	140	nS
T _f	Turn-Off Fall Time		--	60	130	nS
Q _g	Total Gate Charge	V _{DS} =480, V _{Gs} =10V, ID=7A (Note 3,4)	--	29	38	nC
Q _{gs}	Gate-Source Charge		--	7	--	nC
Q _{gd}	Gate-Drain Charge		--	14.5	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _s	Maximum Continuous Drain-Source Diode Forward Current	--	--	7.5	A	
I _{SM}	Maximum Plused Drain-Source DiodeForwad Current	--	--	28	A	
V _{SD}	Drain-Source Diode Forward Voltage	I _d =7A	--	--	1.5	V
trr	Reverse Recovery Time	I _s =7A, V _{Gs} =0V di _f /dt=100A/ μ s (Note3)	--	320	--	nS
Qrr	Reverse Recovery Charge		--	2.4	--	μ C

*Notes 1, L=15.7mH, IAS=7.5A, VDD=50V, RG=25Ω, Starting T_J =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

4, Essentially Independent of Operating Temperature

Typical Characteristics

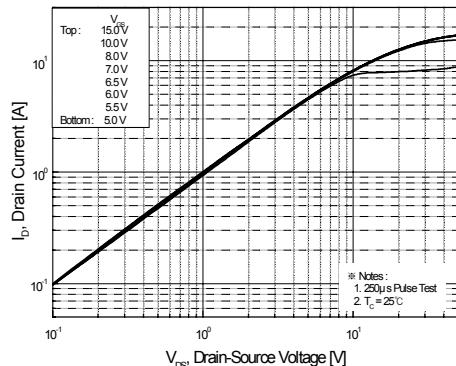


Figure 1. On-Region Characteristics

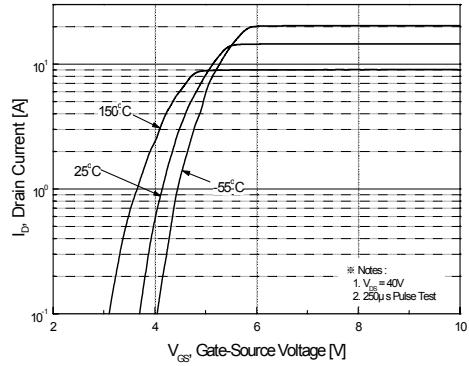


Figure 2. Transfer Characteristics

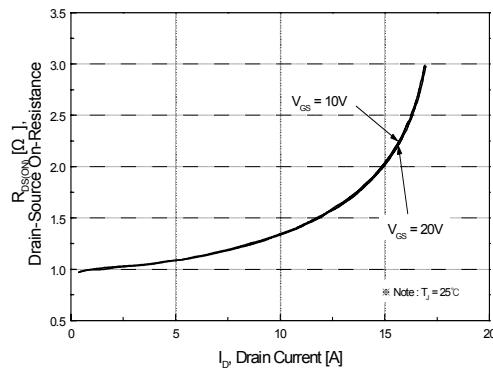


Figure 3. On-Resistance Variation vs
Drain Current and Gate Voltage

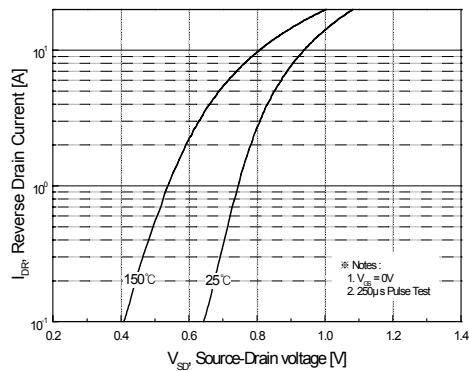


Figure 4. Body Diode Forward Voltage
Variation with Source Current
and Temperature

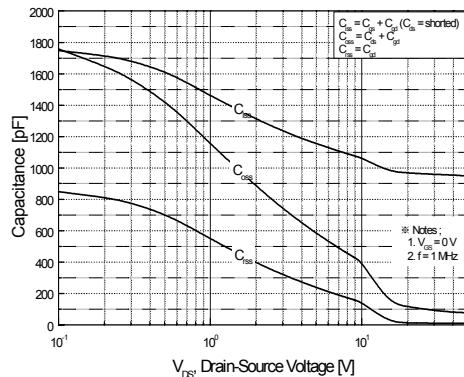


Figure 5. Capacitance Characteristics

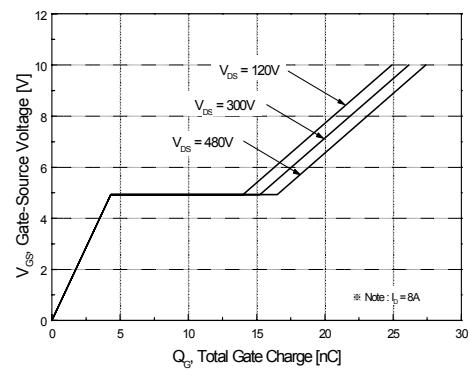


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

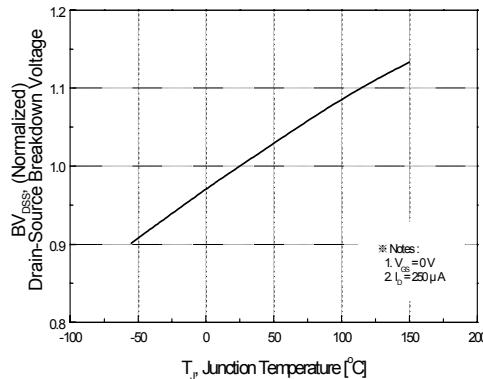


Figure 7. Breakdown Voltage Variation vs Temperature

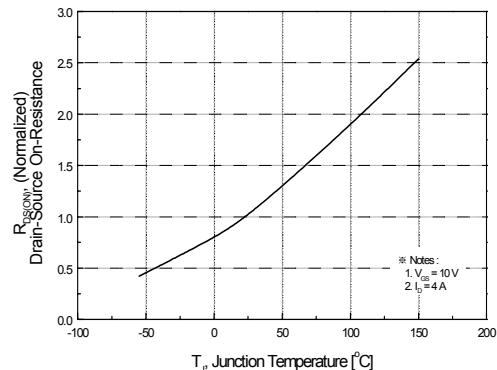


Figure 8. On-Resistance Variation vs Temperature

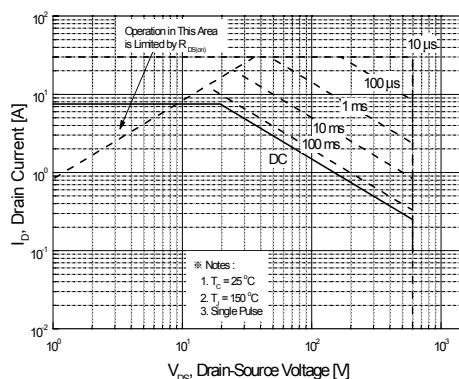


Figure 9-1. Maximum Safe Operating Area for WFP8N60

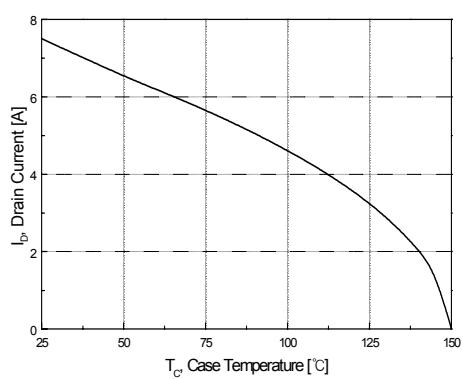


Figure 10. Maximum Drain Current vs Case Temperature

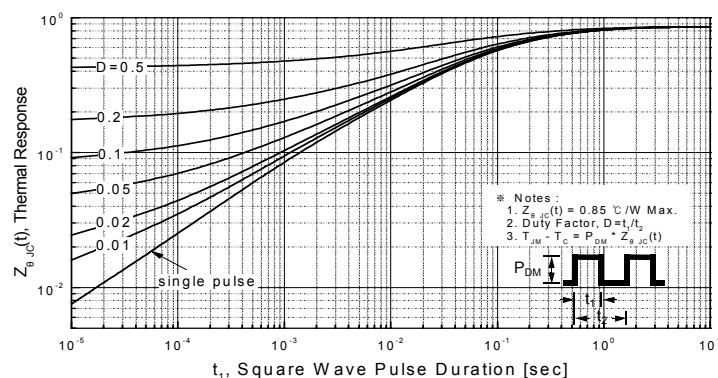
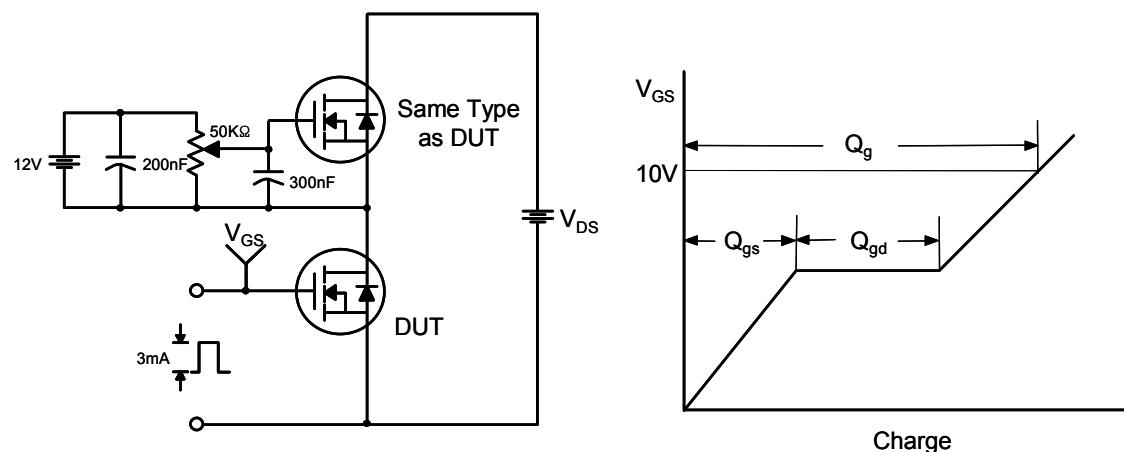
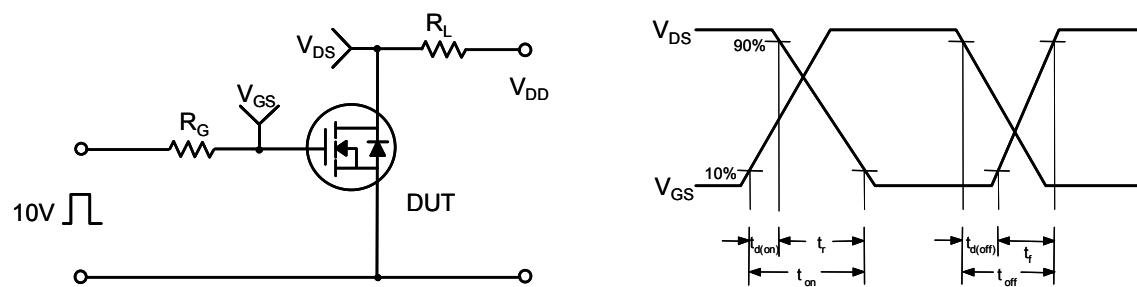
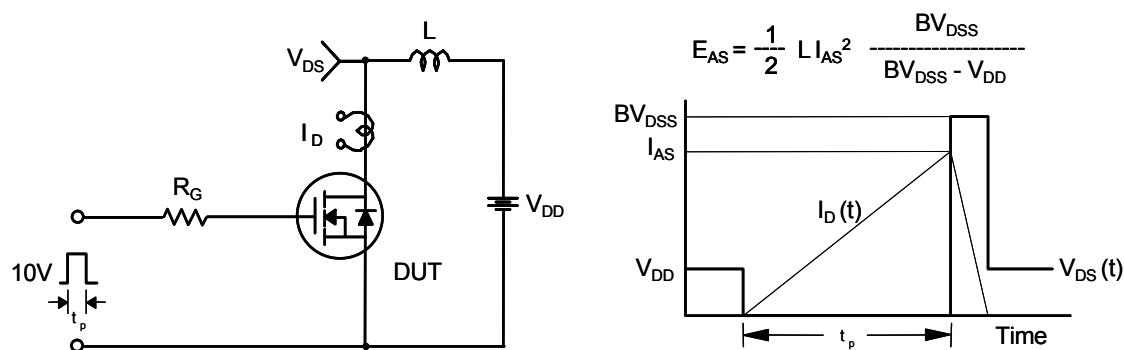


Figure 11-1. Transient Thermal Response Curve for WFP8N60

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms


Peak Diode Recovery dv/dt Test Circuit & Waveforms

